

MATERIAL DECLARATION SHEET



Material Number	SF-0603SP-M			
Product Line	Multilayer Time Lag Chip Fuse			
Compliance Date	08/30/2017			
RoHS Compliant	YES	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Body	Glass Ceramic	1.5860	Boron	7440-42-8	7.39	5.3455%	72.337%
				Carbon	7440-44-0	2.11	1.5261%	
				Aluminum	7429-90-5	18.65	13.4915%	
				Silicon	7440-21-3	15.24	11.0240%	
				Potassium	7440-09-7	0.53	0.3834%	
				Oxygen	7782-44-7	56.08	40.5658%	
2	Termination	Silver with Glass	0.3838	Silver	7440-22-4	92.25	16.1505%	17.505%
				Oxygen	7782-44-7	2.23	0.3904%	
				Zinc	7440-66-6	1.64	0.2871%	
				Silicon	7440-21-3	0.10	0.0175%	
				Bismuth	7440-69-9	3.78	0.6618%	
3	Fuse Link	Silver	0.0094	Silver	7440-22-4	100	0.3559%	0.429%
4	Plating	Nickel	0.0943	Nickel	7440-02-0	100	4.3020%	9.578%
		Tin	0.1157	Tin	7440-31-5	100	5.2771%	
5	Red Mark	Composite	0.0019	Oxygen	7782-44-7	50.86	0.0442%	0.0870%
				Aluminum	7429-90-5	16.02	0.0139%	
				Silicon	7440-21-3	18.74	0.0163%	
				Potassium	7440-09-7	0.57	0.0006%	

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				Zinc	7440-66-6	9.82	0.0085%	
				Iron	7439-89-6	3.99	0.0035%	
6	Masking Layer	Glass Ceramic	0.0014	Boron	7440-42-8	9.83	0.0063%	0.064%
				Carbon	7440-44-0	1.81	0.0012%	
				Aluminum	7429-90-5	16.85	0.0108%	
				Silicon	7440-21-3	15.58	0.0100%	
				Potassium	7440-09-7	0.53	0.0003%	
				Oxygen	7782-44-7	55.40	0.0355%	
				Total weight	2.1925			

This Document was updated on: **10-26-23**

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.